



SHENZHEN KINGSPEC ELECTRONICS TECHNOLOGY CO., LTD.

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	KingSpec *					RING POSSIBILITIE
	XF-XXX Specifications					
	Item	Model Name	XF-XXX			
Kir	Overview	Dimensions	L42.0mm * W22.0mm * H3.5mm ±0.15mm			
		Interface	M. 2, PCI-e Gen4 x4 NVME Rev. 1.4			
		Support OS	Windows 7, Windows 8.1, Windows 10, DOS, Linux, Unix			
		Capacity	256GB	512GB	1TB	2TB
Kir	Performan ce	NAND Flash	3D NAND	3D NAND	3D NAND	3D NAND
		Seq. Read(MB/s)	4400~4600	4700~4900	4700~4900	4800~5100
		Seq. Write(MB/s)	1300~1500	2600~2800	4400~4600	4200~4400
		TBW	300TB	600TB	1200TB	2400TB
		Random 4k Read IOPS	560K (2TB)			
		Random 4k Write IOPS	765K (2TB)			
		Random Acc. time	0.22ms (2TB)			
	Electrica 1	Input Voltage	DC 3.3V±5%		6	
		Idle Mode(W)	0.82W(2TB)			
		Max (W)	5. 48W (2TB)	MIL		
	Reliabili ty	Read endurance	Infinite			
		Data Retention	10year @ 25°C			
		MTBF	1million hours			
		ECC	4K LDPC			
Kin	als	Function	Automated Bad Block Management			
	Environme nt	Option Temperature	0~+70°C	MIL		
		Storage Temperature	-20~+75℃			
		Humidity	5-95%			
	Warranty	Limited 3-year warranty with free technical support				
	Certifica tion	CE, ROHS, FCC, REACH				
	Status	MP	NO EOL		W	
				Mi		

